

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-4. (canceled).

5. (currently amended): A porous resin obtained by a process comprising the steps of:
removing the solvent from ~~the a~~ photosensitive resin composition ~~according to claim 1~~
comprising a polyamic acid resin, a photosensitive agent, a dispersible compound dispersible in
the polyamic acid resin, and a solvent, to form a state that the dispersible compound is
dispersed in the polyamic acid resin;
removing the dispersible compound, to make the photosensitive resin composition
porous; and
curing the photosensitive resin composition.

6. (original): The porous resin according to claim 5, wherein the process further
comprises the step of patterning the photosensitive resin composition by exposure and
development.

7. (original): The porous resin according to claim 5, which is used as an insulating layer
of a circuit board.

8. (original): The porous resin according to claim 5, which is used as an insulating layer of a wireless suspension board.

9. (original): A circuit board comprising an insulating layer comprising the porous resin according to claim 5.

10. (original): The circuit board according to claim 9, which is a wireless suspension board.